



Click [here](#) for the 3D model.

**General Information**

Series	KONNEKT Auto COG
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	77.62 mg
Chip Size	1206-2
Shelf Life	78 Weeks
MSL	1

**Specifications**

Capacitance	0.094 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10.638 GOhms

**Dimensions**

L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	3.2mm +/-0.4mm
B	0.5mm +/-0.25mm

**Packaging Specifications**

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.